





# The development of the readout ASIC for the pair-monitor with SOI technology ~irradiation test~

Yutaro Sato Tohoku Univ. 29<sup>th</sup> Mar. 2010

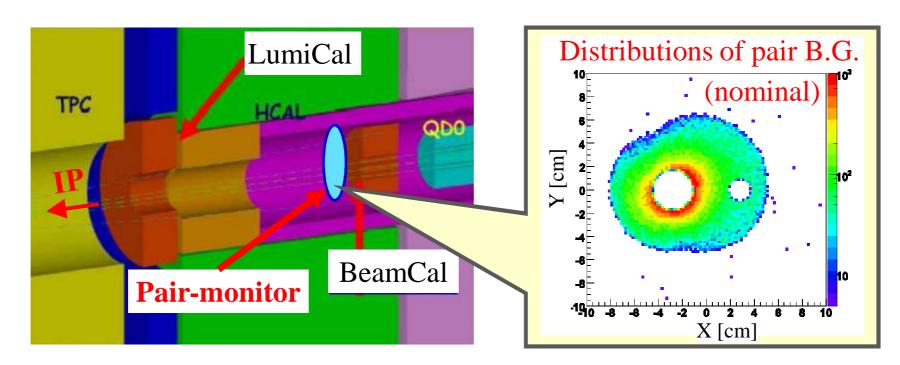
- **♦** Introduction
  - > Pair-monitor
  - > SOI technology
- ◆ Prototype ASIC
  - > Design
  - > Irradiation test

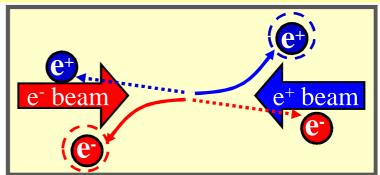


#### **Pair-monitor**

Pair-monitor is a silicon pixel detector to measure the beam profile at IP.

- The distribution of the pair B.G. is used.
  - The same charges with respect to the oncoming beam are scattered with large angle.
  - The scattered particles have information on beam shape.
- The location will be in front of the BeamCal.



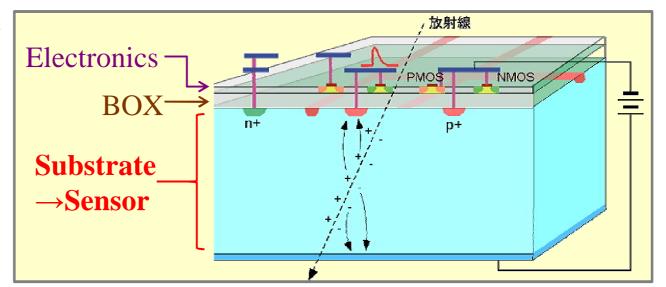


## Development of Pair-monitor with SOI technology

The pair-monitor is developed using the SOI technology.

#### **SOI** (Silicon On Insulator) pixel detector

- SOI pixel group at KEK is currently developing.
- The sensor and electronics are integrated in the SOI substrate.
  - Monolithic device
  - > High speed
  - Low power
  - > Thin device
  - > Low material



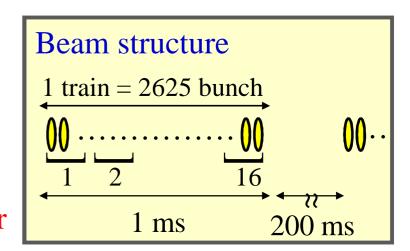
- The prototype ASIC for the pair-monitor was fabricated via the MPW Run organized by the SOI pixel group.
- This prototype is not monolithic (Substrate is not a sensor).



## Requirement to readout ASIC

## **Required performance**

- 1. Time resolution : < 260 nsec (less than bunch space)
- 2. Noise level : < 1000 e (typical signal level : 15,000 e)
- 3. Radiation tolerance : > a few Mrad/year
- 4. Time-dependent measurement
  - Measure the pixel hit count in 16 time slice per train,
    and hit counts are read out during the inter-train gap of 200 ms.
- → The prototype readout ASIC was designed to satisfy these requirements.





## **Prototype readout ASIC**

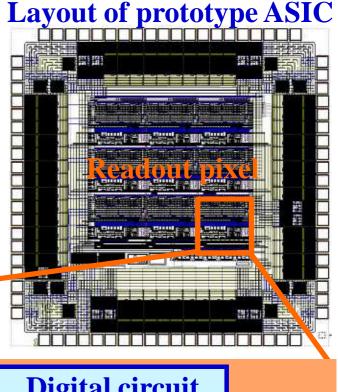
• Process : FD-SOI CMOS 0.20 μm

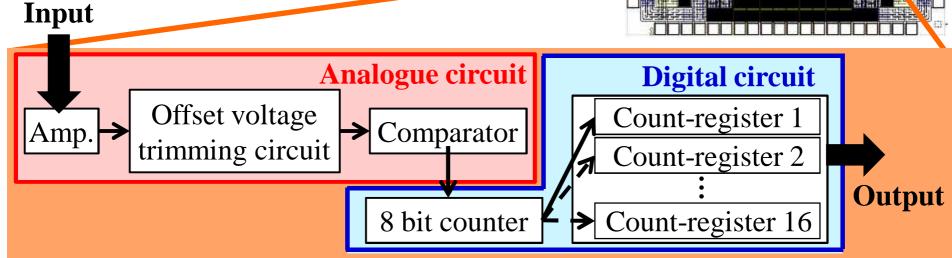
• Chip size : 2.5 x 2.5 mm<sup>2</sup>

• # of pixels : 9 (3x3)

• Pixel size : 390 x 350 μm<sup>2</sup>

• Each cell has different detector capacitance.







#### **Irradiation test**

Irradiation test was performed to test the radiation tolerance

and observe the radiation effect.

• X-ray generator : Rigaku FR-D

- Target : Cu (~ 8 keV)

• Doses: up to 2 Mrad

- #photons was evaluatedby the pin-diode.



- All the photons are assumed to be absorbed within an attenuation length ( $\lambda \sim 66 \ \mu m$ ).
- Silicon density :  $d = 2.33 \text{ g/cm}^3$



#### Radiation effect

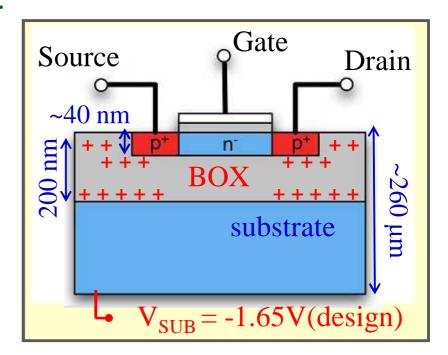
There are two types of radiation effect.

#### Single event effect (SEE)

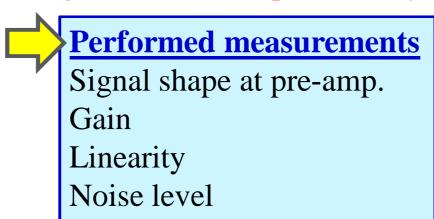
- Caused by single energetic particle.
- → SOI device is known as rad-hard for SEE.

#### **Total dose effect (TDE)**

 Caused by charge trapped in the oxide layer.



→ Oxide trapped charge could be compensated by the substrate voltage.

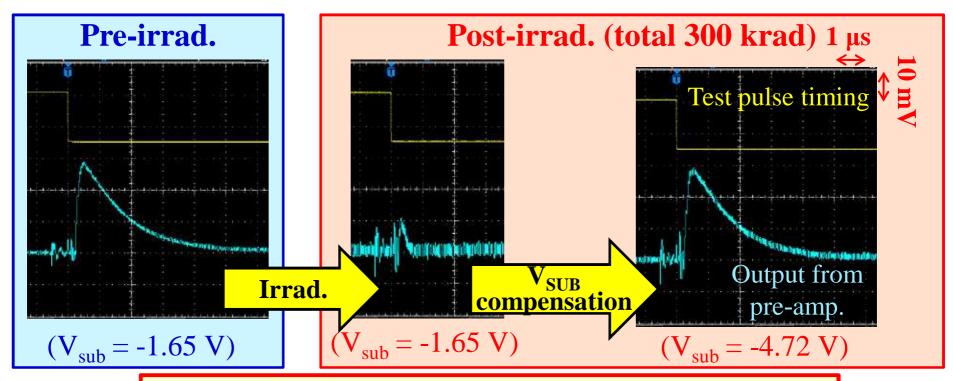




# Signal shape

The signal shape at the pre-amp. was compared.

• By irradiation, the signal shape becomes smaller.



The signal shape of post-irradiation can be returned to that of pre-irradiation by  $V_{SUB}$  compensation.

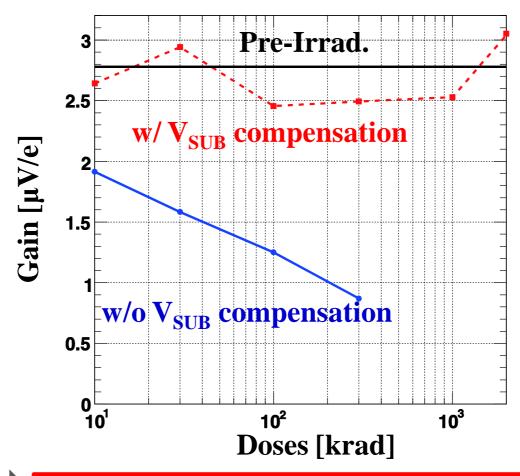
• The transistor was shorted due to large 1 Mrad irradiation, however similarly the signal shape can be returned by  $V_{SUB}$ .



## Gain

The threshold scan was performed and the gain was compared.

• By the irradiation, the gain becomes smaller.





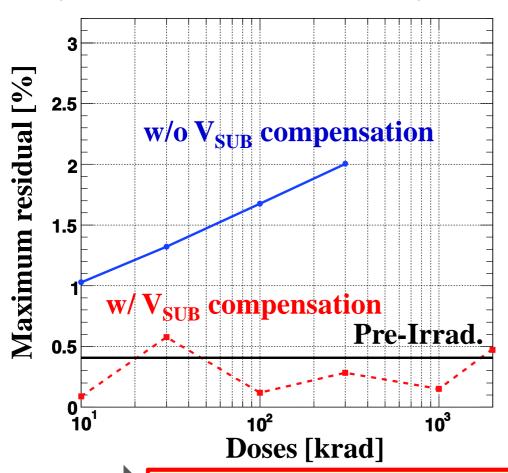


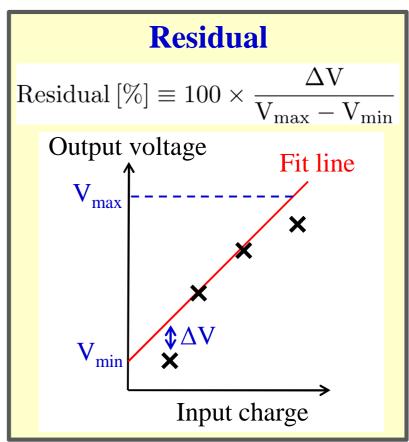
# Linearity

The threshold scan was performed and the linearity was compared.

(fitting region :  $7,000 \sim 45,000 e$ )

• By the irradiation, the linearity becomes worse.





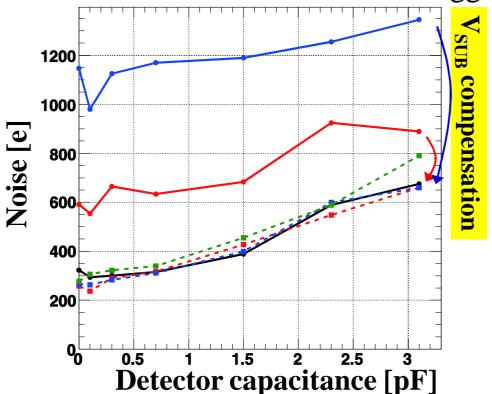
The linearity can be restored by V<sub>SUB</sub> compensation.



#### **Noise level**

The noise level was compared.

• By irradiation, the noise level becomes bigger.



Pre-Irrad. (100krad)

Post-Irrad. (300krad)

Post-Irrad. (2Mrad)

Dashed line means w/ V<sub>SUB</sub> compensation.

The noise level returns to that at pre-irrad. by the  $V_{SUB}$  compensation.



The radiation tolerance up to 2 Mrad was confirmed and oxide trapped charge was compensated by  $V_{SUB}$ .



## Summary

#### The development of the pair-monitor with SOI technology was started.

- The first prototype which is only readout ASIC was produced and the irradiation test were performed successfully.
  - > The radiation tolerance up to 2 Mrad was confirmed.
  - > The oxide trapped charge was compensated by the substrate voltage.



#### Plan

- Irradiation test ( $\gamma$ -ray or electron beam)
- Production of the monolithic prototype

# Backup

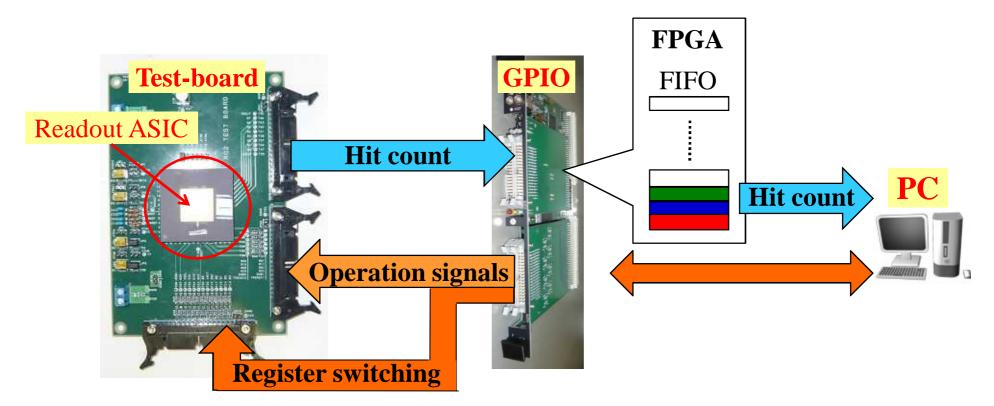


## Test system

The operation test was performed.

## **Test system**

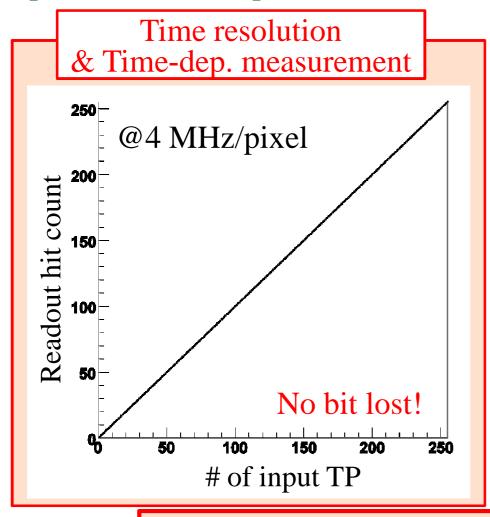
- GNV-250 module was used for the operation and readout.
  - KEK-VME 6U module
- The test-sequence by GPIO is controlled by a PC.

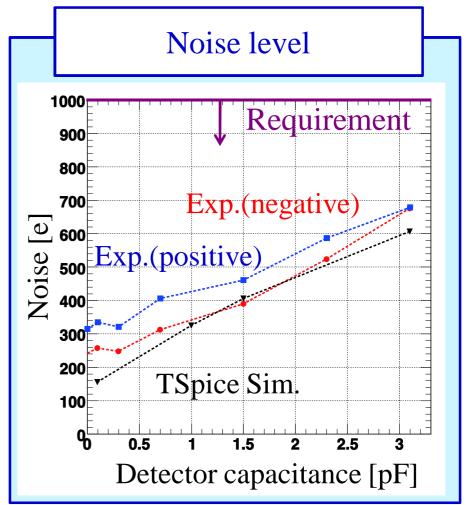




## **Operation test**

Operation test was performed successfully.





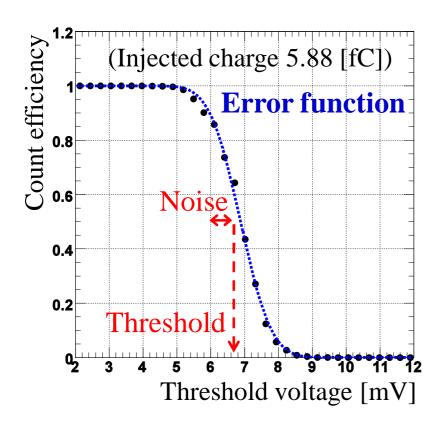
Prototype meets the requirement of time resolution, time-dependent measurement and noise level.



#### Threshold scan

Threshold scan was performed.

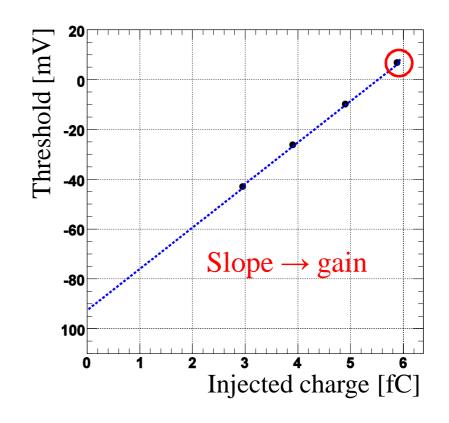
• Fit to error function (S-curve)



• Threshold:  $6.886 \pm 0.009 \,[\text{mV}]$ 

• Noise:  $0.7152 \pm 0.0128$  [mV]

The gain was estimated to convert the noise into equivalent noise electrons.

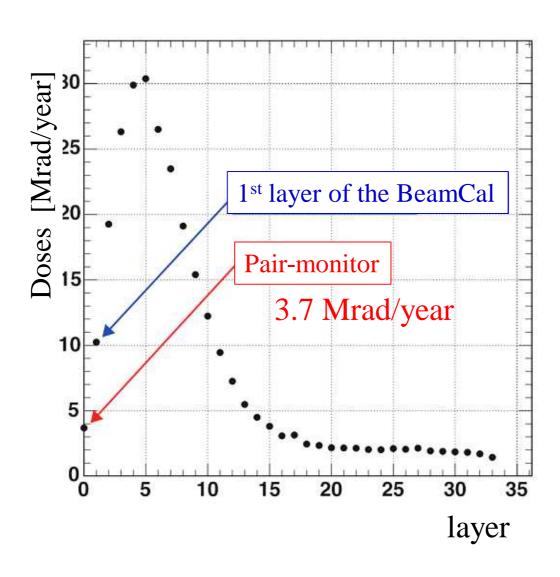


• Gain: 16.94 [mV/fC]

Noise : ~260 electrons



## **Radiation doses**





#### **Radiation doses**

**Total Doses = (#photon)** × (**Doses per a photon**)

#### The number of photons

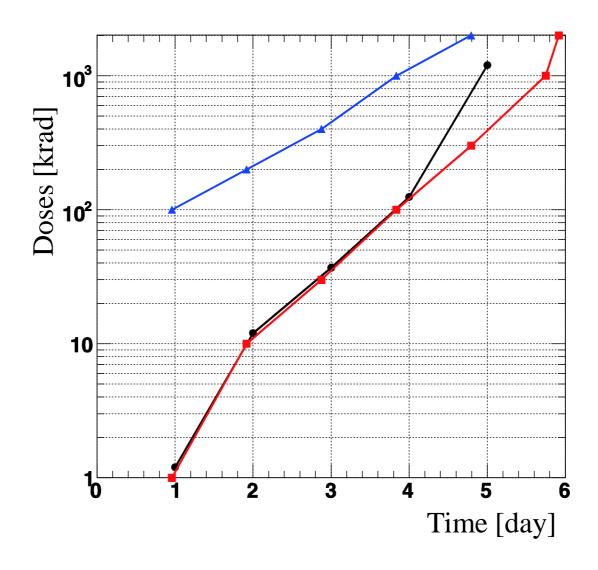
- Evaluated by the photoelectron of diode.
  - $k = 2.5 \times 10^9 [photon/\mu A]$

#### Doses per a photon

- Energy of photon: 8.19 keV
  - Weighted average of  $K\alpha$  (8.04 keV) and  $K\beta$  (8.91 keV)
  - All the photons are assumed to be absorbed within an attenuation length ( $\lambda \sim 66 \ \mu m$ )
- Silicon density  $d = 2.33 \text{ g/cm}^3$

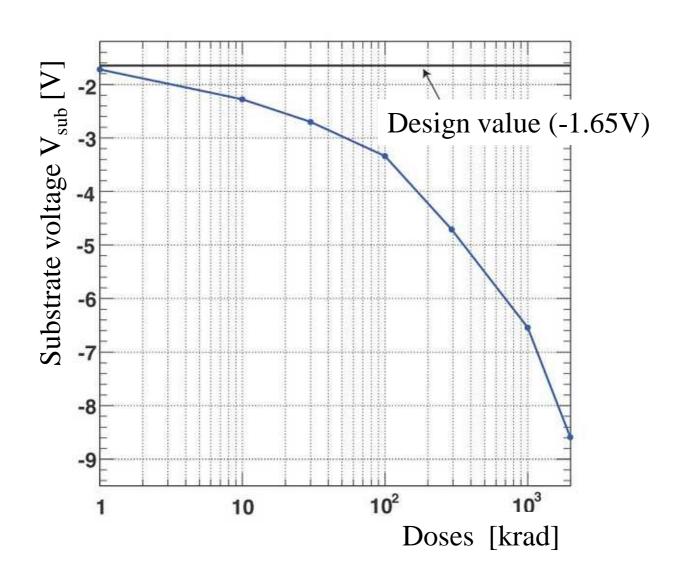


## Radiation doses



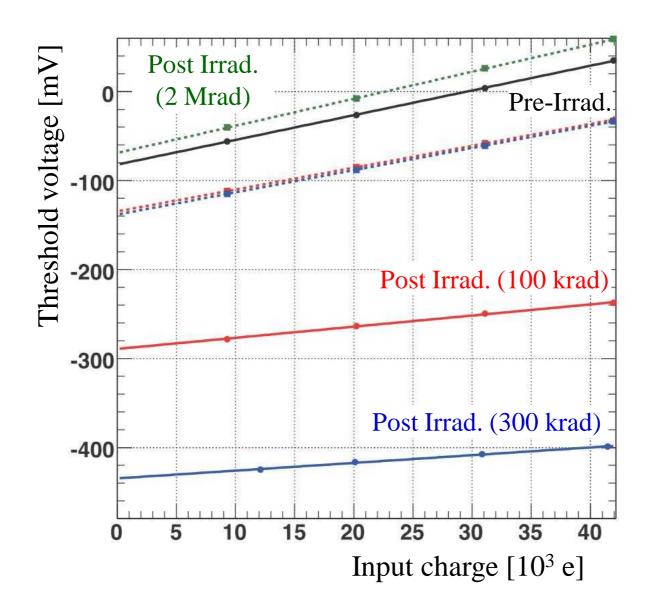


# Substrate voltage (V<sub>sub</sub>)





## Threshold scan





## Residual

